

SUBJECT: ECH-U (B) Series Film Chip Capacitor

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RECOMMENDED REPLACEMENT : ECH-U(X) or ECH-U(C)

OTHER DETAILS: The ECH-U(B) was the original design for the SMT Film Capacitor. The termination surface of the capacitor is coated with a metallic spray which leaves a flat surface on the face of the termination with no rounding metallization on the edge. This may cause the part to “tombstone” under certain soldering conditions for capacitors with case sizes smaller than either 1913 or 1206.

The parts with the “X” suffix have a termination that is made by dipping the capacitor into a conductive resin. The conductive resin leaves a rounded contour around the edges of the capacitor.

This design helps to avoid tombstoning for the small case size Film Capacitors.

The ECH-U(C) is a physically larger part and is not prone to tombstoning.

Please refer to chart below for recommendations:

Soldering Methods	Not Recommended	Recommended Series	
Wave	ECH-U(B) 16, 50 Vdc	ECH-U(C) 50, 100 Vdc	-
Reflow			ECH-U(X) 10, 16, 50 Vdc